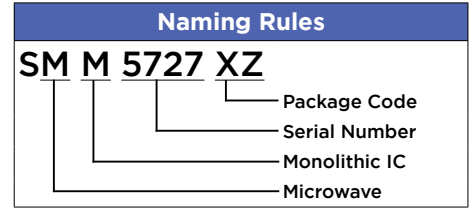


E-Band MMICs

Features

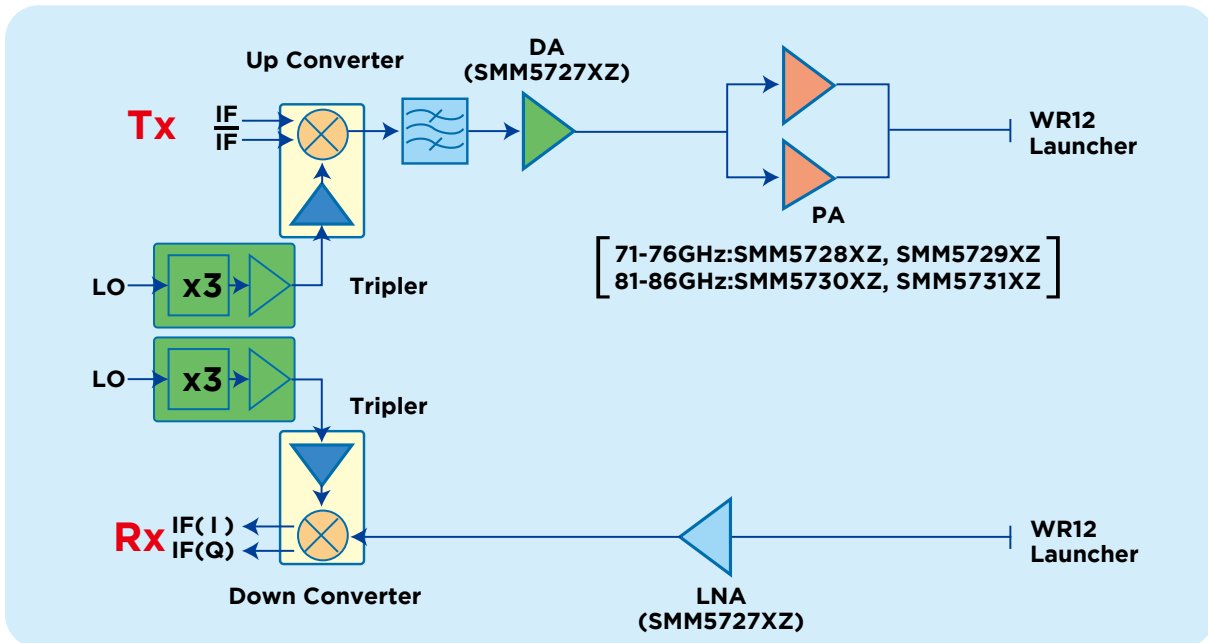
- Low Cost Surface Mount Type Devices
- Flip Chip Form with Solder Ball
Solder Ball Diameter : 140µm
Solder Ball Pitch : 300µm
- Small size
- High integrated
- Chip Level Protection against Humidity
- RoHS Compliance



Specifications (PA and LNAs)

Part Number	Freq. (GHz)	NF (dB)	Gain (dB)	P1dB (dBm)	VDD (V)	IDD(RF) (mA)	Package	Function
SMM5727XZ	71-86	5 (71-76GHz) 5.5 (81-86GHz)	21.5 (71-76GHz) 20.5 (81-86GHz)	12(71-76GHz) 11(81-86GHz)	6	60	WLCSP	LNA and DA
SMM5728XZ	71-76	12	25	17	6	410		PA
SMM5729XZ	71-76	12	25	17	6	410		
SMM5730XZ	81-86	12	27	17	6	410		
SMM5731XZ	81-86	12	27	17	6	410		

Note: Tc=+25°C



Product Photo

Outline of WLCSP MMIC

